PRODUCT SPECIFICATION

CS2002B-D-YSXFDYN-101

V1.0

February 13, 2009

Version	Description	Date
Version V1.0	Description First release	Date Feb 13, 2009

REVISION RECORD

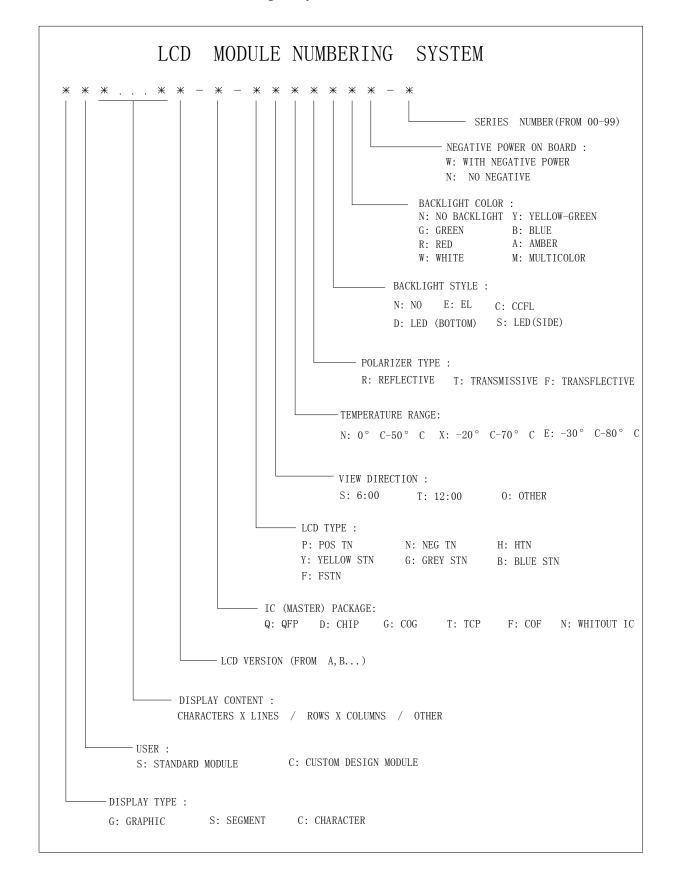
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1. TYPE NUMBER AND DESCRIPTION

Type Number:	CS2002B-D-YSXFDYN-101
Description:	20 Characters X 2 Lines
LCD Panel:	Yellow-green STN, Positive, Transflective
Viewing angle:	6H
Operating Temperature:	$-20\ {}^{0}\mathrm{C} - 70\ {}^{0}\mathrm{C}$
Storage Temperature:	$-30\ {}^{0}\mathrm{C} - 80\ {}^{0}\mathrm{C}$
Backlight:	Bottom, Yellow-green LED
Controller:	ST7066U-OA Or Equivalent
IC Package:	Bonding
Logic Voltage:	5.0V
Fixed hole:	φ 3.5mm



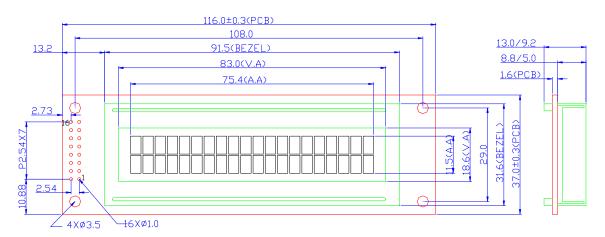


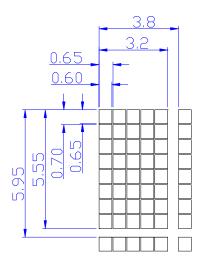
2. LCD Module Numbering System



3. MECHANICAL SPECIFICATIONS:

ITEM	STANDARD VALUE	UNIT
NUMBER OF CHARACTERS	20CHARACTERS X 2 LINES	
CHARACTER FORMAT	5 X 8 DOTS	
MODULE DIMENSION	116.0(W) X 37.0(H) X13.0(T)	mm
EFFECTTVE DISPLAY AREA	83.0(W) X 18.6(H)	mm
CHARACTER SIZE	3.2(W) X 5.55(H)	mm
CHARACTER PITCH	3.8(W) X 5.95(H)	mm
DOT SIZE	0.60(W) X 0.65(H)	mm
DOT PITCH	0.65(W) X 0.70(H)	mm
APPROX WEIGHT	TBD	g
LCD TYPE	Yellow-green STN, Transflective	
DUTY AND BIAS	1/16 DUTY; 1/5 BIAS	
VIEWING DIRECTION	6:00	
BACK LIGHT	Bottom, Yellow-green LED	





* Remark : Non-specific tolerance refers this model. (±0.2mm)

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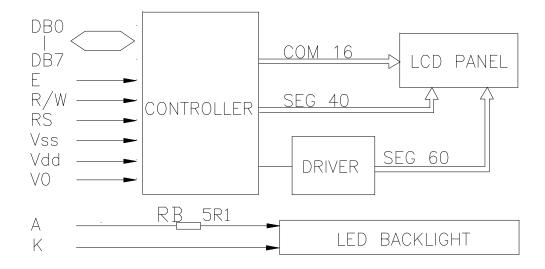
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4. ELECTRICAL BLOCK DIAGRAM

4.1 PINS DEFINITION

PIN	SYMBOL	FUNCTION
1	Vss	Power Supply(GND)
2	Vdd	Power Supply(+5V)
3	Vo	Contrast Adjust
4	RS	Instruction/Data Register Select
5	R/W	Data Bus Line
6	E	Enable Signal
7-14	DB0-DB7	Data Bus Line
15	А	Power Supply for LED+
16	K	Power Supply for LED-

4.2 ELECTRICAL BLOCK DIAGRAM



4.3 DISPLAY CHARACTER ADDRESS CODE

DISPLAY	POSITION	1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18	19	20
	ADDRESS	00	01	02	03	04	05	06	07	08	09	0A	0B	0C	0D	0E	0F	10	11	12	13
	ADDIL23	40	41	42	43	44	45	46	47	48	49	4A	4B	4C	4D	4E	4F	50	51	52	53

5. ABSOLUTE MAXIMUM RATINGS

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Supply Voltage (Logic)	Vdd – Vss	-	0	7.0	V
Supply Voltage (LCD Drive)	Vdd – V0	-	0	11.5	V
Input Voltage	Vi	-	-0.3	Vdd +0.3	V

5.1 Electrical Maximum Ratings (Ta=25deg C)

5.2 Environmental Conditions

ITEM	SYMBOL	CONDITION	MIN	MAX	UNIT
Operating Temp	Topr	Dry	-20	70	deg C
Storage Temp	Ttsg	Dry	-30	80	deg C

6. ELECTRICAL SPECIFICATIONS

6.1 Electrical Characteristics at Ta=25 deg C, Vdd = 5V + / - 5%

ITEM	SYMB OL	CONDITIO N	MIN	TY P	MAX	UNIT
Supply Voltage (logic)	Vdd-V ss	-	4.5	5	5.5	V
Supply Voltage (LCD)	Vdd-V 0	Vdd = 5V	4.3	4.7	5.0	V
Input signal voltage	V-ih	"H" level	0.7Vdd	-	Vdd	V
(for E, DB0-7,R/W,RS)	V-il	"L" level	0	-	0.6	V
Supply Current (logic)	Icc	-	0.9	1	1.2	mA
Supply Current (LCD)	Io	-	0.15	0.22	0.27	mA
Supply Voltage (LED)	V-led	see note 1	3.9	4.1	4.4	V
Supply Current (LED)	If	see note 1	150	200	300	mA

Note 1: LED backlight chips are arranged in two branched of 2 in series

6.2 TIMING SPECIFICATIONS at Ta = 25 deg C, Vdd = 5V+/-10%, Vss =0V

6.2.1Write mode

ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	_	25	ns



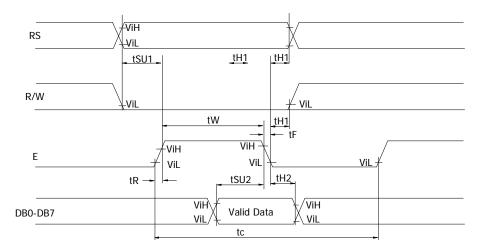
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsul	40	-	ns
R/W and RS hold time	tH1	0	-	ns
Data set-up time	tsu2	60	-	ns
Data hold time	tH2	10	-	ns

6.2.2 Read mode

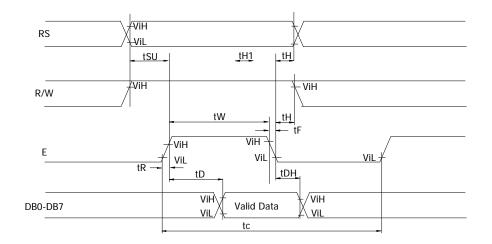
ITEM	SYMBOL	MIN	MAX	UNIT
E cycle time	tc	1200	-	ns
E rise time	tR	-	25	ns
E fall time	tF	-	25	ns
E-pulse width (H, L)	tw	140	-	ns
R/W and RS set-up time	tsu	40	-	ns
R/W and RS hold time	tH	10	-	ns
Data output delay	tD	-	120	ns
Data hold time	tDH	20	_	ns

6.2.3 Timing Diagram

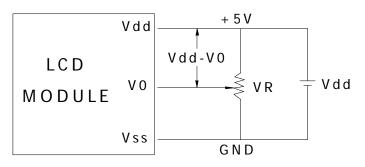
WRITE MODE TIMING DIAGRAM



READ MODE TIMING DIAGRAM



7. POWER SUPPLY FOR LCD MODULE



Vdd-V0: LCD Driving Voltage VR: 10K - 20K

8. ELECTRO-OPTICAL CHARACTERISTIC

ITEM	SYMB OL	CONDI TION	MIN.	TYP.	MAX.	UNIT	REF.
Contrast	CR	25℃		12			Note1
Rise Time	tr	25℃		160	240	ms	Note2
Fall Time	tf	25℃		100	150	ms	note 2
Viewing Angle	θ1-θ2	25℃			60	DEG	Note 3
viewing Angle	Ø1, Ø2	23 C	-40		40	DEO	Note 5
Frame Frequency	Ff	25℃		70		Hz	note 2

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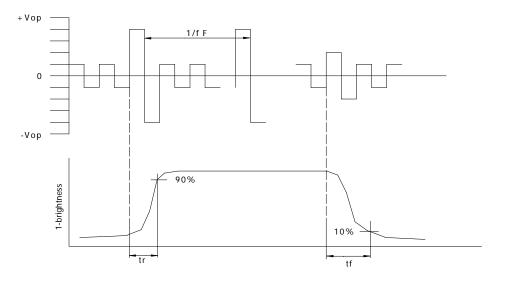
Note(1): Contrast ratio is defined under the following condition:

- CR= <u>brightness of selected condition</u> brightness of non-selected condition
- (a). Temperature-----25C
- (b). Frame Frequency-----64Hz
 - Easterntronic LCD Group

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- (c). Viewing angle----- $\theta=0, \emptyset=0$
- Operating Voltage---4.7V (d).

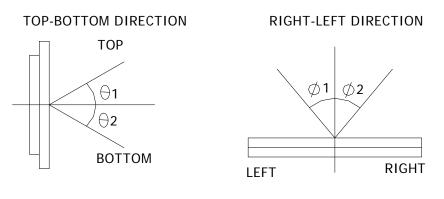
Note(2): definition of response time:



Condition:

- Temperature-----25C (a).
- Frame Frequency-----64Hz (b).
- Viewing angle----- $\theta=0, \emptyset=0$ (c).
- Operating Voltage---4.7V (d).

Note(3): definition of view angle:



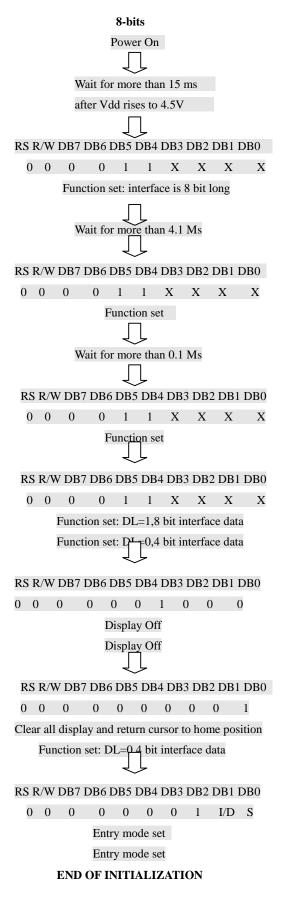


9. INSTRUCTION TABLE

Function	R	R	D	D	D	D	I	D	D	D	Description	Execu
	S	/	B	B	B	B	B	B	B	B		Time*
		V	7	6	5	4	3	2	1	0		(Max)
Clear	0	0	0	0	0	0	0	0	0	1	Clears entire display and returns the cursor to	1.64mS
Display											home position (address 0)	
Return	0	0	0	0	0	0	0	0	1	Х	Return the cursor to the home position. DD	1.64mS
Home											RAM contents remain unchanged. Set DD	
											RAM address to zero.	
Entry	0	0	0	0	0	0	0	1	1	S	Set cursor moving direction and enable the	40µS
mode									/		shift of the display. These operations are	•
set									Ľ		performed during data write/read of DD	
											RAM/CG RAM. 1/D=1: increment; 1/D=0:	
											decrement; S=1: whole display shift when data	
											is written.	
Display	0	0	0	0	0	0	1	Г	\mathbf{c}	B		40µS
ON/OFF	Ũ	Ŭ	Ŭ	Ű	Ŭ	Ŭ	1		$\left \right $		cursor(B) ON/OFF. D=1:display ON; D=0:	торю
control											display OFF. C=1:Cursor ON; C=0:cursot OFF.	
control											B=1:Blink ON; B=0, Blink OFF.	
Cursor or	Δ	Δ	Δ	Δ	Δ	1	C	D	τ	X		40µS
	U	U	U	U	U	I	3 /			Δ	1 2	40µ5
Display shift							c				changing DDRAM contents. $S/C=1$: Display	
SIIII							C				Shift; S/C=0:Cursor move. R/L=1:shift to right;	
F (*	0	0	0	0	1	Г		1			R/L=0:shift to left.	40 C
	U	U	U	U	I		r	T	X	X		40µS
Set						L					display lines (N) and character font (F).DL=1:	
											8 bits; DL=0: 4 bits. N=1: 2 lines; N=0: 1 lines.	
	_	_	_								F=1: 5X11 dots; F=0: 5X7 dots.	
Set CG	0	0	0	1		1	40	C	J		Set CG RAM address. CG RAM data is sent	40µS
RAM add											and received after this setting.	
	0	0	1			A	D	D)		Set DD RAM address. DD RAM data is sent	40µS
RAM Add											and received after this setting.	
Read BF	0	1	B		_	1	40	С	_		Read BUSY FLAG (BF) and the contents of the	0µS
& Addr			F								address counter. BF=1: internal operation;	
											BF=0: can accept instruction.	
Write	1	0			W	/R	ľ	ГF	3		Write data into DD RAM or CG RAM.	40
Data to					Γ)A	T	Ά				µS**
RAM												•
Read Data	1	0	R	E	ĊΑ	D	Γ)A	ΔT	A	Read data from DD RAM or CG RAM.	40
from												μS**
RAM												•



10. INITIALIZATION BY INSTRUCTION



4-bits Power On Wait for more than 15 mS after Vdd rises to 4.5V RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 Function set: DL=1,8 bit interface data. Wait for more than 4.1 Ms ΓΓ RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 1 DL=1,8 bit interface data Wait for more than 0.1 Ms RS R/W DB7 DB6 DB5 DB4 $0 \quad 0 \quad 0 \quad 0 \quad 1 \quad 0$ DL=0,4 bit interface data RS R/W DB7 DB6 DB5 DB4 0 0 0 0 1 0 0 0 N F X X RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 1 0 0 0

RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 0 0 0 1

RS R/W DB7 DB6 DB5 DB4 0 0 0 0 0 0 0 0 0 1 I/D S

END OF INITIALIZATION



11. SOFTWARE EXAMPLES

0-DIT OF LKF	S-BIT OPERATION TO CHARACTERS & TIMES										
Function	RS F	RW D7	7 D6	D5	D4	D3	D2	D1	DO	DISPLAY	DESCRIPTION
Power on											Initialization. No display
delay											appears.
Function set	0 0	0 C	0	1	1	0	0	Х	Х		Sets 8-bit operation, 2-line
											display and 5*7 dots character
											font.
Display OFF	0 (0 C	0	0	0	1	0	0	0		Turn off display.
Display ON	0 0	0 C		0	0	1	1	1	0		Turn on display and cursor.
Entry Mode	0 0	0 C	0	0	0	0	1	1	0		Set mode to increment the
set											address by one and to shift the
											cursor to the right, at the time
											of write to the DD/CG RAM.
											Display is not shifted.
Write data to	1 (0 0	1	0	0	1	1	1	1	<u>0</u>	Write "O". Cursor incremented
CG/DD RAM											by one and shift to right.
Write data to	1 (0 0	1	0	1	0	0	1	0	<u>OR</u>	Write "R". Cursor incremented
CG/DD RAM											by one and shift to right
Write data to		•		·	·	·				ORIENT	Write "I" "E" "N" "T".
CG/DD RAM											
Set DDRAM	0 0) 1	1	0	0	0	0	0	0	ORIENT	Set RAM address so that the
address											cursor is positioned at the 9 th
											position
Write data to		•		·	·	·				ORIENT DS	Write "D" "S".
CG/DD RAM					-				V		
Cursor or	0 0	0 0	0	0	1	0	0	Х	Х	ORIENT DS	Shift only the cursor position
display shift											to the left.
Write data to		•		·	·	·				ORIENT DIS	Write "I" "S"
CG/DD RAM											

8-BIT OPERATION 16 characters X 1 lines

4-bit operation (4-bits 1 line)

Function	RS	RW	/ D7	D6	D5	D4	Display	Description	
power on delay								Initialization. No display appears.	
Frnction set	0	0	0	0	1	0		Sets to 4 -bit operation. In this case, operation is handled as 8-bits by initialization, a nd Only this instruction completes with one write.	
Frnction set	0 0	0 0	0 0	0 0	1 X	0 X		Sets 4 -bit operation, 1-line display and 5*7 dot character font. (number of display lines and character fontscannot be changed hence after.)	
Display ON/OFF Control	-	0 0	0 1		0 1		_	Turn on display and cursor.	
Entry Mode Set	0 0	0 0	0 0	0 1	0 1	0 0	_	Turn on display and cursor.	
Write data to CG/DD/ARM			0 1	1 1	0 1	0 1		Write "O". Curaor incrementer by one and shift to right.	
	same as 8-bit operation								

12.Quality units

12.1 Purpose

This standard for quality assurance should define the quality of LCD module products to customer by EASTERNTIONIC LCD GROUP.

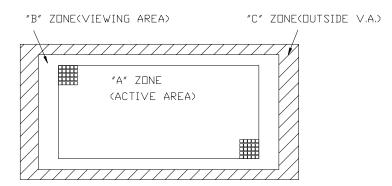
12.2 Scope

This document defines general provisions as well as inspection standards for LCD module supplied by EASTERNTIONIC LCD GROUP, except for those with special requirements from customer.

12.3 Definition

12.3.1 Definition of area

- A Zone: Active area.
- B Zone: Viewing area
- C Zone: Outside viewing area.



12.3.2 Definition of size

Large size(L): $1 \sim 6$ pcs LCD screens are cut out of from each $14" \times 16"$ mother glass. Middle size(M): $7 \sim 50$ pcs LCD screens are cut out of from each $14" \times 16"$ mother glass. Small size(S): more than 50 pcs LCD screens are cut out of from each $14"\times16"$ mother glass.

12.4 Quality Specification

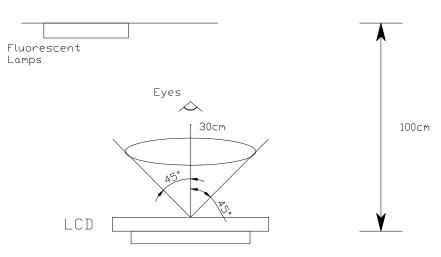
12.4.1 Conditions of Cosmetic Inspection

12.4.1 Test should be conducted under the following conditions:

Ambient temperature :22 \pm 5°C. Ambient humidity: $65 \pm 20\%$ RH Ambient Luminance: 40-watt fluorescent lamp. An appearance test should be conducted by human sight at approximately 30 cm distance



from the LCD module under fluorescent light. Distance between LCD and fluorescent lamps should be 100 cm or more. Viewing direction for inspection is 45° from vertical against LCD.



12.4.1.2 When test the model of transmissive product must add the reflective plate.

12.4.2 Sampling plan

Unless otherwise agreed in writing, the sampling inspection shall be applied to the incoming inspection of customer.

- Lot size: Quantity of shipment lot per model
- Sampling type: Normal inspection, single sampling
- Sampling Level: Level II
- Sampling table: GB/T2828.1.1(GB-national standard of China)

12.4.3 Classification of defects and Acceptable quality level

Defects and classified as either a major or minor defect defined as bellows:

- Major defect: It is a defect that is likely to result in failure or to reduce materially the usability of the product for the intended function.

- Minor defect: It is a defect that will not result in functioning problem with deviation calssifiec.

The AQL for major and minor defects is defined as follows:

Partition	Definition	AQL
Major defect	Functional defective as product	0.4
Minor defect	Satisfy all functions as product but not satisfy cosmetic standard	1.0



12.4.4 Applicable instrument

- LCD module tester

- Multimeter
- Caliper
- Defect size filming standard

12.4.5 Inspection quality criterion

12.4.5.1 LCD panel part

The inspection specification as following list:

Classify	Item	Description of defects	Inspectio	on criterion	Drawing specification
Major defect	1.Non-display	Product no function	Not	accept	
	2.LCD with wrong view direction`	Difference in Spec.	Not	accept	
	3.Segment missing	Part or all pattern do not light up	Not	accept	
	4.Occur high current	Current exceed designed value	Not	accept	
	5. LC leakage	LC does not fulfill the glass cell	Not	accept	
	6.Deviation from drawing	LCM Dimension difference from drawing and over tolerance	0	to dimensions e specification	
	7.Wrong type applied	Wrong polarizer attachment	Not	accept	
		Pin attached wrong type applied	Not	accept	
	8.Incorrect pins quality	Pin attached wrong quantity applied	Not	accept	
Minor defect	9.Pattern deformation	Segment fatter or smaller	Dimension (mm) A≤0.1	Acceptable number Not count (Should not be connected to next dot)	



[]			0.10 <a≤0.15< th=""><th>1 pc / dot(only</th><th></th></a≤0.15<>	1 pc / dot(only	
			0.10 <a≤0.15< td=""><td>segment)or</td><td></td></a≤0.15<>	segment)or	
				less	
				2 pcs / cell or	
				less (Should not be	
				connected to	
				next dot)	
			D (0.40	Not count	
			B ≤ 0.10	NOL COUNT	
Minor	10.Pinholes	Black spot/white	1. large size		
defect		spot at activated	-	in't be found at	
		state		e and will not	
			U	er electronic test	
			2. Middle si		
			Diameter(mm $\Phi \le 0.15$	n) Accept QTY	
				Not count	X
			0.15<Φ≤0.25		$\Phi = (X+Y)/2$
			0.25<Φ≤0.35		$\Psi - (\Lambda + 1)/2$
			$\Phi > 0.35$		
			3. Small siz		
				n) Accept QTY	
			Φ≤0.15	Not count	
			$0.15 < \Phi \le 0.25$		
			$0.25 < \Phi \le 0.30$	1	
			$\Phi > 0.30$		
			4. For the	1	
			accept i		
				s less than or	
			equal to	half of one	
			lattice's	w one defect in	
			5. Only allo one segm	ow one defect in	
			6. The ne		
				between two	
			pinholes		
			Remarks:	Regarding the	
			product in	negative type	
			(including TN,	STN and FSTN),	
				riving voltage, the should be less or	
				$\Phi \leq 0.2$). If the	
			driving voltage	e is lower 0.3V	
				l voltage, it should	
				oltage, it can not ite dot base on	
			abnormal voltag		
				-	



11.Blemishes	Black spot/dust	Positive panel:	<u> </u>
and foreign	on	1.A zone	
matters	LCD(non-display	- Large size LCD	
)	Accept if can't find at 1m	
		distance and will not enlarge	X
		under electronic test:	$\Phi = (X+Y)/2$
		-Middle size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		$0.15 < \Phi \le 0.25$ 3	
		0.25<Φ≤0.35 1	
		$\Phi > 0.35$ 0	
		-Small size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \leq$ 0.15 Not count	
		$0.15 < \Phi \le 0.25$ 2	
		$0.25 < \Phi \le 0.30$ 1	
		$\Phi \! > \! 0.30$ 0	
		2.B zone	
		1.5 times of acceptable	
		largest diameter size of Zone	
		A	
		3.C zone	
		Notcount.	
		Negative panel:	
		1. A zone	
		-Large size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \leq$ 0.15 Not count	
		$0.15 < \Phi \le 0.30$ 4	
		$0.30 < \Phi \le 0.50$ 1	
		$\Phi \! > \! 0.50$ 0	
		-Middle&small size LCD	
		Diameter(mm) Accept QTY	
		$\Phi \le 0.15$ Not count	
		$0.15 < \Phi \le 0.25$ 3	
		$\Phi > 0.25$ 0	
		$\Phi > 0.25$ 0 2. B zone	
		1.5 times of acceptable	
		largest diameter size of Zone	
		A	
		A 3.C zone	
		No count	
		The nearest diatance	
		allowed between two black	
		spot is 20mm	
		spot is zomin	
	1		



Г	12.Black	Saratah an alaga	Positiva popel	
	lines and	Scratch on glass or polarizer	Positive panel: 1.A zone	
		-		
	scratches	surface.And	- Large size LCD	
		foreign linear	Accept if can't find at 1m	
		matters in LCD	distance and will not enlarge	
			under electronic test.	
			-Middle size LCD	
			Diameter(mm) Accept QTY	
			$W \le 0.02$ Not count	
			$0.02 < W \le 0.03, L \le 4$ 2	
			$0.03 < W \le 0.05, L \le 3$ 2	
			$0.02 < W \le 0.03$,L >4 0	
			$0.03 < W \le 0.05, L > 3$ 0	
			W>0.05 As the spot criteria.	
			1	
			-Small size LCD	
			Diameter(mm) Accept QTY	
			W≤ 0.02 Not count	
			$0.02 < W \le 0.03, L \le 4$ 2	
			$0.03 < W \le 0.05, L \le 2$ 1	
			$0.02 < W \le 0.03, L \ge 4$ 0	
			$0.02 < W \le 0.05, L > 2$ 0	
			W > 0.05 As the spot criteria.	
			w > 0.05 As the spot efficient.	
			2.B zone	
			1.5 times of acceptable largest	
			diameter size of Zone A	
			3.C zone	
			Notcount.	
			Toteount.	
			Negative panel:	
			1. A zone	
			-Large size LCD	
			Diameter(mm) Accept QTY	
			$W \le 0.02$ Not count	
			$0.02 < W \le 0.03, L \le 5$ 3	
			$0.02 < W \le 0.03, L \le 3$ 3 $0.03 < W \le 0.05, L \le 4$ 2	
			$0.03 < W \le 0.03, L \le 4$ 2 $0.02 < W \le 0.03, L > 5$ 0	
			$0.02 < W \le 0.05, L > 3 = 0$ $0.03 < W \le 0.05, L > 4 = 0$	
			W>0.05 As the spot criteria.	
			-Middle size LCD	
			Diameter(mm) Accept QTY	
			$0.02 < W \le 0.03, L \le 4$ 2	
			$0.03 < W \le 0.05, L \le 2$ 2	

			$\begin{array}{llllllllllllllllllllllllllllllllllll$	
Mintor defect	13. Scratch on PI coating	PI coating scratched	The visible scratch of A zone can not be accepted at 30cm view distance.	
Mintor defect	14. Rainbow	Arches,circular or parallel colorful spread	According to the limit specimen	
Mintor defect	15. Bubbles or wrinkles in polarizer	Bubbles or wrinkles between polarizer and glass	A zone: The visible defect can not be accepted at 30cm view distance. B zone: Not count	
Mintor defect	16. Position of polarzer attachment	Wrong polarizer attachment in position or dimension	Polarizer protruding from edge of glass and exceeding/within the maximum external dimension of LCD	
Mintor defect	17. Ink printing defect	17.1Inkline/patternbroken	Not accept	



		17.2 Ink pattern/line jagged 17.3 Light leakage 17.4 Ink printing	less thar width, o specimer When white lig of pinho printing to the pin	f the thick n equal to r accordin activated ht appear ile or scra misalignu nhole spec the thick	with with s in the atch due ment.Acc	segment he limit current position e to ink ccording n.	
		pattern/line uneven	than 1/2W. Reject when W1-W2≤1/3W				
Mintor defect	18. Pin defect	18.1 Corrosion or foreign material on terminal legs 18.2 Pin deviation over tolerance	Pinincomingdefectoxidized,damage(includingpitplatingdamaged),excessepotonbottomglassorterminlegs.Notaccept.According to the specification				
Mintor defect	19. Chipped glass on comer	19.1 Chip in lead contact area.	a a≤5mm	b b≤W	c c≤T	accept QTY	ITD
			L>5m m a <l L<5m m</l 	b≤W	c≤T	3	
		19.2 Others	Not exc width of		c≤T	3	
Mintor defect	20. Glass	a	b	c	accept QTY		
			a≤5mm	Not exceed 1/2 width of seal	c≤T	3	
Mintor	21. Clipped electrode pad	21.1Glass chip on ITO edge	a	b	c	accept QTY	ITO



defect			a≤4mm (and not exceed 4 ITO termina 1	b≤W/4	c≤T	3			
		21.2 Glass chip on ITO back	a a≤5mm	b b≤W/3	c c≤T	accept QTY 3			
			assiinii	USW/3	C \si	5			
Mintor defect	22. Mechanical	Extended crack inspector shall	b	I	accept	QTY			
	damage	attempt to remove the chip with	b≤W/4		2				
		tweezers,re-eval uate if the remaining defect is still a crack or a chip							
Mintor	23.Gla	ass cracks	Not accept						
defect									
The min defect Q Large siz	Remark: The minimum space between any 2 defects(spot,dirt) should more than 20mm, and max. allowed defect QTY in total: Large size LCD: Zone A \leq 5/unit, Zone B \leq 5/unit; Middle size LCD: Zone A \leq 3/unit, Zone B \leq 3/unit;								
		$A \le 3$ /unit, Zone $B \le 2$ $A \le 2$ /unit, Zone $B \le 2$,						



12.4.5.2 Other part

The inspection specification as following list:	The inspection	specification	as following list:
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NO.	Items	Criterion of defects	AQL	
1	Backlight	 Lumination source flickers. Using spot, lines and contamination standard of LCD to judge the spots or scratches defect on backlight. 		
		3. Not allow unlighted on backlight.		
		4. Colour and luminance of backlight should correspond its specification.	Major	
2	PCB,COB	1.COB seal may not have pinholes larger than0.2mm or contamination.		
		2.COB seal surface may not have pinholes through to the IC.3. The height of COB should not exceed the height indicated in the assembly diagram.	Minor Major	
		4. Beyond 2mm of the seal area, there may not have sealant on the PCB.	Minor	
		5.No oxidation or contamination on PCB connector.		
		6.Parts on PCB should correspond the characteristic, and not allow wrong parts, missing parts or additional parts.		
		7.The jumper on the PCB should correspond to the characteristic.	Minor	
		8.The solder which gets on bezel,LED pad,zebra pad or screw hole pad should be smoothed down.	Major	
		1. No unmelted solder pastes on the PCB.	Minor	
3	Soldering	g 2. No cold solder joints,solder connection missing,oxidation of solder.		
		3. No short circuits in components on PCB.	Minor	
4 General 1. No oxidation, contamination, curv Appearance interface Pin of TCP.		1. No oxidation, contamination, curves, cracks or bends on interface Pin of TCP.	Minor	
		2. No solder residue or solder balls on product.	Minor	
		3. The IC on TCP may not be damaged.	Major	
		4. The residual rosin or tin oil of soldering(component or chip component) is not turned into brown or black colour.	Minor	
		5. Packing method correspond the specification.	Major	
		6. Dimension and structure correspond the specification sheet.	Major	
		7. No dirt and break on the heat seal.	Major	

12.5 Reliability

Item	Condition	Criterion				
High temperature operation	$+70^{\circ}\text{C}\pm2^{\circ}\text{C}$, 8 ho					
Low temperature operation	$-20^{\circ}\text{C} \pm 2^{\circ}\text{C}$, 8 ho	1.Total current consumption				
Humidity	Operation	40° C $\pm 2^{\circ}$ C ,93% ± 2 % RH,8 hours	should be below double of initial			
	Storage	40 °C \pm 2 °C ,93% \pm 2%RH, 24 hours	value. 2.Cosmetic defects should not be			
High temperature storage	$+80^{\circ}C \pm 2^{\circ}C$, 10 h	happened				
Low temperature storage	$-30^{\circ}\text{C}\pm 2^{\circ}\text{C}$, 10 h					
Thermal shock	-20°C∼+70°C					
storage	60min~60min, 5 cy					
Vibration test	Amplitude:0.7~1.0 in each direction(X					
Shock test	To be measured aft					
	80cm high on the c					
	state.(weight≥15k					
	Weight <15Kg, dro					
	E	Dropping method corner dropping A corner: once				
	G B	A Edge dropping A B,C,D edge: once				
	•	BOcm Face dropping E,F,G face: once Concrete Surface				
Remark: The function test shall be conducted after 4 hours storage at the normal						
temperature and humidity after removed from the test chamber.						

The LCD module shall not fail the following reliability test.

13. PRECAUTION FOR USING LCM

1. LIQUID CRYSTAL DISPLAY (LCD)

LCD is made up of glass, organic sealant, organic fluid, and polymer based polarizers. The following precautions should be taken when handing,

(1). Keep the temperature within range of use and storage. Excessive temperature and humidity could cause polarization degredation, polarizer peel off or bubble.

(2). Do not contact the exposed polarizers with anything harder than an HB pencil lead. To clean dust off the display surface. Wipe gently with cotton. Chamois or other soft material soaked in petroleum benzin.

(3). Wipe off saliva or water drops immediately. Contact with water over a long period of time may cause polarizer deformation or color fading, while an active LCD with water condensation on its surface will cause corrosion of ITO electrodes.

(4). Glass can be easily chipped or cracked from rough handing. especially at corners and edges.

(5). Do not drive LCD with DC voltage.

2. Liquid Crystal Display Modules

2.1 Mechanical Considerations

LCM are assembled and adjusted with a high degree of precision. Avoid excessive shocks and do not make any alterations or modifications. The following should be noted.

(1). Do not tamper in any way with the tabs on the tabs on the metal frame.

(2). Do not modify the PCB by drilling extra holes, changing its outline, moving its components or modifying its pattem.

(3). Do not touch the elastomer connector, especially insert an backlight panel (for example, EL).

(4). When mounting a LCM make sure that the PCB is not under any tress such as bending or twisting. Elastomer contacts are very delicate and missing pixels could result from slight dislocation of any of the elements.

(5). Avoid pressing on the metal bezel, otherwise the elastomer connector could be deformed and lose contact, resulting in missing piels.

2.2. Static Electricity

LCM contains CMOS LSI's and the same precaution for such devices should apply, namely

(1). The operator should be grounded whenever he/she comes into contact with the module. Never touch any of the conductive parts such as the LSI pads, the copper leads on the PCB and the interface terminals with any parts of the human body.

(2). The modules should be kept in antistatic bags or other containers resistant to static for storage.

(3). Only properly grounded soldering irons should be used.

(4). If an electric screwdriver is used, it should be well grounded and shielded from commutator sparks.

(5). The normal static prevention measures should be observed for work clothes and working benches; for the latter conductive (rubber) mat is recommended.

(6). Since dry air is inductive to statics, a relative humidity of 50-60% is recommended.

2.3. Soldering

(1). Solder only to the I/O terminals.

(2). Use only soldering irons with proper grounding and no leakage.

(3). Soldering temperature: 280 $^{\circ}C \pm 10^{\circ}C$

(4). Soldering time: 3 to 4 sec.

(5). Use eutectic solder with resin flux fill.

(6). If flux is used, the LCD surface should be covered to avoid flux spatters. Flux residue should be removed after wards.

2.4. Operation

(1). The viewing angle can be adjusted by varying the LCD driving voltage V0.

(2). Driving voltage should be kept within specified range; excess voltage shortens display life.

(3). Response time increases with decrease in temperature.

(4). Display may turn black or dark blue at temperatures above its operational range; this is (however not pressing on the viewing area) may cause the segments to appear "fractured".

(5). Mechanical disturbance during operation (such as pressing on the viewing area) nay cause the segments to appear "fractured".

2.5. Storage

If any fluid leaks out of a damaged glass cell, wash off any human part that comes into contact with soap and water. Never swallow the fluid. The toxicity is extremely low but caution should be exercised at all the time.

2.6. Limited Warranty

Unless otherwise agreed between EASTERNTRONIC and customer, EASTERNTRONIC will repiace or repair any of its LCD and LC, which is found to be defective electrically and visually when inspected in accordance with EASTERNTRONIC acceptance standards, for a period on one year fron data of shipment. Confirmation of such date shall be based on freight documents. The warranty liability of EASTERNTRONIC is limited to repair and/or replacement on the terms set forth above. EASTERNTRONIC will not responsible for any subsequent or consequential events. 14. Declaration of conformity regarding the limitation of dangerous substances

深圳易事通液晶显示模块有限公司

SHENZHEN EASTERNTRONIC LCM CO., LTD.

4F, B3 Building, FuYuan Industrial Zone, FuYong Town,

BaoAn District, ShenZhen, P.R. China

DECLARATION OF CONFORMITY REGARDING THE LIMITATION OF DANGEROUS **SUBSTANCES**

WE, SHENZHEN EASTERNTRONIC LCM CO., LTD,

Declare that the product of CS2002B-D-YSXFDYN-101 complies with: The directive 2002/95/EC Dated 2003/01/27 regarding the limitation of dangerous substances, in particular to clause 4 which forbids the use of the following elements:

●Lead

• Mercury

● Cadmium

•Hexavalant chromium

Polybrominated biphenyls

• Polybrominated diphenylethers

And to the annex which points out the exempted implementations

 \Box To the directive 73/23/eec dated 1973/02/19 and the standard EN60335-1 regarding prohibition of following elements:

• 0ils containing polychlorinated biphenyl

Asbestos

Radioactive substances

Name: Ding

SHENZHEN EASTERNTRONIC LCM CO., LTD.

Issued on Feb 13, 2009

According with the proposal of Technical Adaption Committee (TAC) of a limit of 0.1% by weight for lead hexavalent chromium, mercury, PBBs and PBDRs and 0.01% by weight for Cadmium.